

# ACKNOWLEDGEMENT RECEIPT

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## Title of Invention

Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking

Submission Type : Information Disclosure Statement

Application Number:

10/050507



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First Named Applicant: Teck Lee

Attorney Docket Number: MTI-31607

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File Listing:

Doc. Name	File Name	Size (Bytes)	Date Produced (yyyymmdd)
us-ids	MTI-31607a-usidst.xml	1414	2005-11-10
us-ids	us-ids.dtd	7763	2005-11-10
us-ids	us-ids.xsl	12026	2005-11-10
package-data	MTI-31607a-pkda.xml	1733	2005-11-10
package-data	package-data.dtd	27025	2005-11-10
package-data	us-package-data.xsl	19263	2005-11-10
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